

JOM Call for papers

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Manuscript Deadline: *April 1, 2019*

The Alloy Phases Committee is seeking papers on the topic of
Advanced Electronic Interconnection

Papers are invited for this special topic covering recent advances of bonding technologies for 2.5D and 3D IC, wide-band-gap (WBG) semiconductors, and flexible electronics.

Original research papers should be 3,000-6,000 words with up to 8 figures maximum; review papers should be 6,000-10,000 words with up to 15 figures maximum.

Detailed author instructions are available at:
<http://www.tms.org/AuthorTools/>

Keywords for this topic:
Advanced processing, alloy phases, electronic materials, joining, phase transformations

Guest Editor for the *JOM* topic is Shih-kang Lin:
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If you are interested in submitting a paper, upload your manuscript at
<https://www.editorialmanager.com/jomj/>

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

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